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(54) **CIRCUIT BOARD AND MANUFACTURING METHOD THEREOF, AND LIGHT EMITTING MODULE**

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(57) **ABSTRACT**

A circuit board including a substrate, a first circuit layer, a first insulating layer, a second circuit layer, and a solder resist layer is provided. The first circuit layer is disposed on the substrate. The first insulating layer is disposed on the substrate and covers a portion of the first circuit layer. The second circuit layer is disposed on the first insulating layer and penetrates a portion of the first insulating layer to electrically connect the first circuit layer. The solder resist layer is disposed on the substrate and covers a portion of the second circuit layer.

